

REMARKS

Applicants respectfully request reconsideration of the prior art rejections set forth by the Examiner under 35 USC sections 102 and 103. Applicants respectfully submit that the claims as now modified clearly distinguish over the references of record cited by the Examiner.

More specifically, Applicants have carefully considered the remarks and analysis of the Examiner with respect to the previously presented claims and the references of record cited by the Examiner. By this amendment, Applicants have modified the claims only for the purpose of eliminating the issue raised by the Examiner concerning the product by process limitations which the Examiner asserted prevented the language relating to the adhesive material from being given patentable weight.

Applicants have modified independent claim 6 to specifically require that the adhesive layer of material is comprised of a material which loses its adhesive characteristics upon application of a specified treatment. Applicants also note that claim 10 which is dependent on claim 6 further specifies that: the adhesive properties of said adhesive sheet are released upon the application of ultra violet light.

Applicants respectfully submit that these modifications eliminate the product by process issue raised by the Examiner as Applicants have now clearly specified the characteristics of the adhesive material layer which is specified in the independent claim. Applicants submit that neither Camien nor any of the remaining references of record teach or suggest this advance in the art. Specifically in regard to the Camien reference, Applicants note that the Camien reference describes securing individual dies "face-down onto [an] epoxy drop" and thereafter removing "any epoxy from circuit side of die." See, for example, steps 2 and 9 described in column 4 at lines 30-45 of the Camien reference cited by the Examiner.

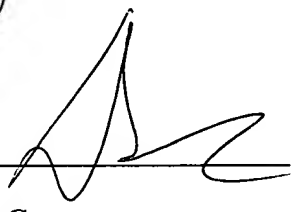
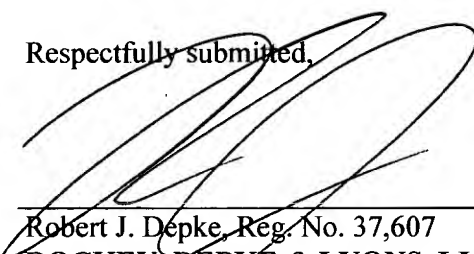
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Applicants note that the present inventors have overcome the shortcomings and deficiencies of the prior art by providing a convenient technique for creating a so-called pseudo-wafer which enables convenient simultaneous processing of a number of known good die thereby eliminating processing inefficiency associated with the processing of defective chips in the manufacture of semiconductor devices. In contrast with the cited prior art which requires separate steps of applying epoxy, placing chips on the surface to which the epoxy is applied and thereafter removing the epoxy, the present invention entirely eliminates the need to separately remove the epoxy from the chips. This is due to the fact that the treatment applied to the adhesive layer enables the convenient removal of the pseudo-wafer from the substrate without requiring the removal of any adhesive residue.

Accordingly, in light of the foregoing, Applicants submit that the modified limitations should be given patentable weight and the claims should be allowed because the prior art does not teach or suggest such a structure. Applicants therefore submit that all claims now stand in condition for allowance.

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Respectfully submitted,



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